

# Surface Mount Superfast Recovery Rectifier

#### **FEATURES:**

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

## **Circuit Diagram & Pin Configuration:**





#### SMB/DO-214AA

#### **Absolute Maximum Ratings and Characteristics**

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	ES3AB	ES3BB	ES3CB	ES3DB	ES3EB	ES3GB	ES3JB	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at $T_c$ = 100 °C	I <sub>F(AV)</sub>	3					А		
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I <sub>FSM</sub>	90					А		
Maximum Forward Voltage at 3 A	V <sub>F</sub>	1 1.25 1.68				1.68	V		
Maximum DC Reverse Current T <sub>a</sub> = 25 °C at Rated DC Blocking Voltage T <sub>a</sub> = 125 °C	I <sub>R</sub>	5 100					μA		
Typical Junction Capacitance at V <sub>R</sub> =4V, f=1MHz	C <sub>j</sub>	45					pF		
Maximum Reverse Recovery Time <sup>(1)</sup>	t <sub>rr</sub>	35					ns		
Typical Thermal Resistance (2)	$R_{ heta_{JA}} \ R_{ heta_{JC}}$	50 16					°C/W		
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150					°C		

<sup>( 1 )</sup> Measured with  $I_{\scriptscriptstyle F}$  = 0.5 A,  $I_{\scriptscriptstyle R}$  = 1 A,  $I_{\scriptscriptstyle ff}$  = 0.25 A.

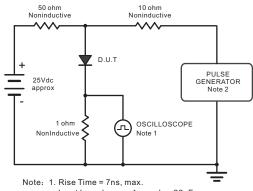
#### Marking

Type number	Marking code				
ES3AB	ES3A				
ES3BB	ES3B				
ES3CB	ES3C				
ES3DB	ES3D				
ES3EB	ES3E				
ES3GB	ES3G				
ES3JB	ES3J				

<sup>(</sup> 2 ) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



#### Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



- Input Impedance = 1megohm,22pF.
  - 2. Ries Time =10ns, max. Source Impedance = 50 ohms.

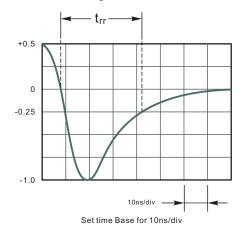


Fig.2 Maximum Average Forward Current Rating

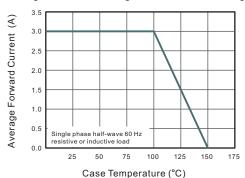


Fig.3 Typical Reverse Characteristics

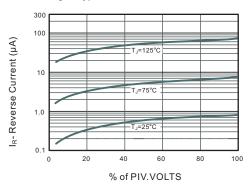


Fig.4 Typical Forward Characteristics

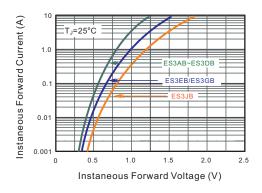


Fig.5 Typical Junction Capacitance

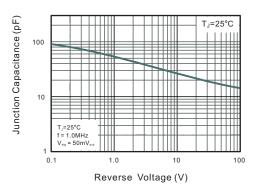
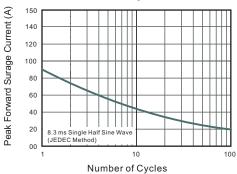


Fig.6 Maximum Non-Repetitive Peak Forward Surage Current

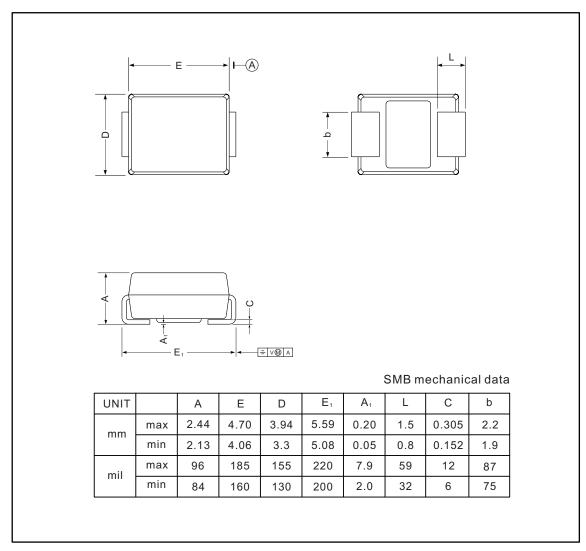




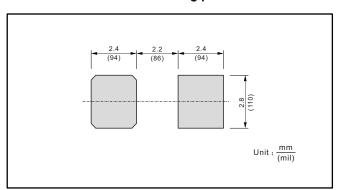
#### PACKAGE OUTLINE

#### Plastic surface mounted package; 2 leads

#### SMB/DO-214AA



#### The recommended mounting pad size





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